

WIREFILM BONDING
FOR ELECTRONIC COMPONENT INTERCONNECTION

ABSTRACT OF THE DISCLOSURE

5 A system (30) is provided for interconnecting a first component (10) having multiple first bonding sites (16) and a second component (12) having multiple second bonding sites (18). The system (30) includes a leadframe (40) coupled to the first component (10) and the second component (12) that advances from a first position (50) to a second position (52). A film tape carrier (32) advances a wirefilm (20) removably coupled to the film tape carrier (32) into the first position (50). The wirefilm (20) includes a substantially planar film (22) and multiple wire strands (14), each wire strand (14) having a first end (24) that contacts a first bonding site (16) and a second end (26) that contacts a second bonding site (18). A film attach tool (62) contacts the first component (10) and the second component (12) with the wirefilm (20) at the first position (50) to interconnect the first component (10) and the second component (12).